

04-27-00

A

Law Offices of Kenneth E. Leeds  
P.O. Box 2819  
Sunnyvale, CA 94087-0819  
Phone: 408-732-9500  
FAX: 408-736-7052  
kleeds@concentric.net  
April 25, 2000

Box Patent Application  
Commissioner of Patents and Trademarks  
Washington, D.C. 20231

jc564 U.S. PTO  
09/558083  
04/25/00

Dear Sir:

Transmitted herewith for filing is a patent application as follows:

Inventor: John Hsieh and Robert M. Tierney  
Assignee: Komag, Inc.  
Title: Removal of Enclosed Glass Parts After Cutting Using Heating and Cooling Techniques  
Docket: K2000003

Also enclosed are:

5 sheets of informal drawings  
3 pages of Declaration  
1 check for \$1524  
1 return receipt postcard

CLAIMS AS FILED

	<u>Claims</u>	<u>Extra</u> <u>Claims</u>	<u>Rate</u>	<u>Additional</u> <u>Fee</u>
Total Claims	49	29	\$18	\$522
Independent Claims	7	4	\$78	\$312
Basic Fee				\$690
Total:				\$1524

A check for \$1524 is enclosed herewith. Please deduct any additional required charges, or credit any overpayment, to deposit account 500794.

This transmittal letter is being filed in triplicate.

Respectfully Submitted,

*Kenneth E. Leeds*

Kenneth E. Leeds  
Reg. No. 30,566  
Attorney for Applicants

Express Mail Label No.:  
EK530766412US

jc809 U.S. PTO  
04/25/00

09558083 042500

EXPRESS MAIL LABEL NO.

EK530766412US

REMOVAL OF ENCLOSED GLASS PARTS AFTER CUTTING  
USING HEATING AND COOLING TECHNIQUES

John Hsieh

JH 4/21/00

Robert M. Tierney

RT. 4/21/00

Background of the Invention

This invention pertains to a method for separating a product piece from one or more waste pieces. This invention also pertains to a method for cutting and separating pieces of glass. This invention also pertains to a method for making a glass substrate for use in magnetic disk manufacturing.

Japanese laid open patent publication 2-92837 discusses a method for cutting and separating a planar glass work piece into a product piece and a waste piece. During the 2-92837 method, the following steps are performed:

1. A circular scribe line is mechanically formed in a circular glass work piece to define a circular waste piece within the glass work piece.
2. The glass work piece is heated from the side containing the scribe line to propagate a crack from the scribe line into the interior of the work piece.
3. The glass work piece is heated a second time. This causes the crack to further propagate into the work piece.
4. A brass chilling tool is cooled by bringing the chilling tool into contact with dry ice. The chilling tool is then applied against the waste piece to cause the waste piece to thermally contract. This chilling tool also pushes against the waste piece to separate the waste piece from the rest of the work piece.

RT. 4/21/00

JH

4/21/00

Japanese laid open publication 7-223828 criticizes the use of the 2-92837 chilling tool, and instead proposes the following method:

1. A scribe line is formed in a glass work piece with a mechanical scribing tool. This results in a crack that propagates partially through the work piece at an angle. The scribe line defines an inner portion of the work piece.
2. A portion of the work piece is heated (from the same side as the scribe line) to propagate the crack entirely through the thickness of the work piece. The crack propagates at an angle relative to the major surface of the work piece.
3. The inner portion of the work piece is pushed downward by a push rod, and separated from the remainder of the work piece.

In summary, the 2-92837 and 7-223828 references discuss mechanically scribing a glass work piece to form a crack in the work piece, and thermally propagating the crack through the work piece.

Another technique for scribing a glass work piece comprises using a laser to cut the work piece into a product piece and waste pieces. Fig. 1 illustrates a glass work piece 1 comprising cuts 2, 3 which extend through the thickness of work piece 1. Cuts 2, 3 separate work piece 1 into an outer waste piece 4, an inner waste piece 5, and a product piece 6 which is subsequently used as a substrate for the manufacture of a magnetic disk. Even though cuts 2, 3 extend through the entire thickness of work piece 1, one must still separate product piece 6 from waste pieces 4 and 5. This is difficult, because waste pieces 4, 5 contact and hold product piece in a manner that does not generally permit one to simply slide the product piece relative to the waste pieces. It is an object of this invention to provide a method for separating a work piece from one or more waste piece.

1           One problem with prior art break-out techniques is that they generate glass  
2 splinters and/or defects in the glass work piece. This reduces production yields. It is an  
3 object of some embodiments of the invention to minimize or reduce the number of  
4 splinters and/or defects generated when one separates a work piece from one or more  
5 waste pieces.

## 6 7 Summary

8           A method in accordance with a first embodiment of the invention comprises the  
9 step of providing a work piece including one or more cuts extending through the work  
10 piece. The cuts define a product piece and one or more waste pieces within the work  
11 piece. The product piece is separated from one of the waste pieces by providing a  
12 temperature difference between the product piece and the waste piece so that one expands  
13 relative to the other (and/or contracts relative to the other). This expansion (and/or  
14 contraction) facilitates separating the work piece from said one of the waste pieces.

15           In one embodiment, the work piece is a brittle material such as glass or glass  
16 ceramic. The cuts can be formed by applying radiant energy (e.g. a laser) to the work  
17 piece. Typically, a cooling fluid (e.g. a liquid or a gas) is applied to the work piece after  
18 application of the laser to form the cut, and ensure that it extends through the thickness of  
19 the work piece.

20           In one embodiment, the temperature difference between the product piece and the  
21 waste piece is greater than 125°C, and preferably greater than 150°C. However, the  
22 temperatures applied to the work piece should not be so extreme as to potentially damage

1 or warp the work piece. Typically the temperature difference is between about 150 and  
2 300°C.

3 In one embodiment, the waste piece partially or completely surrounds the product  
4 piece. In such an embodiment, a temperature difference is provided such that the waste  
5 piece is hotter than the product piece, so that the waste piece is in an expanded state  
6 compared to the product piece.

7 In one embodiment, the temperature difference is provided by placing the waste  
8 piece against the surface of a heating element to thereby heat the waste piece. One or  
9 more channels are formed in the heating element that extend to the surface of the heating  
10 element against which the waste piece is placed. A vacuum is applied to the one or more  
11 channels to generate a force that holds the waste piece flush against the heating element  
12 to thereby prevent the waste piece from warping.

13 In another embodiment, the product piece partially or completely surrounds the  
14 waste piece. In such an embodiment, the temperature difference is provided such that the  
15 product piece is hotter than the waste piece, so that the product piece is in an expanded  
16 state compared to the waste piece.

17 A method in accordance with another embodiment of the invention comprises  
18 separating a product piece (e.g. a substrate used for the manufacture of a magnetic disk)  
19 from inner and outer waste pieces. In one such embodiment, the substrate is separated  
20 from the outer waste piece by heating the outer waste piece so that the outer waste piece  
21 expands relative to the substrate. The substrate (along with the inner waste piece) is then  
22 lifted (or lowered) relative to the outer waste piece to thereby separate the substrate from

1 the outer waste piece. (Alternatively, the outer waste piece can be lifted or lowered  
2 relative to the substrate.)

3         Thereafter, the substrate is heated relative to the inner waste piece, and the inner  
4 waste piece is cooled relative to the substrate, so that the substrate expands relative to the  
5 inner waste piece, and the inner waste piece contracts relative to the substrate. Thus, a  
6 gap develops between the substrate and inner waste piece that facilitates separation of the  
7 substrate from the inner waste piece.

8         In another embodiment, the substrate is heated by placing the substrate in  
9 proximity to, but not in contact with, a heating element. Advantageously, this prevents  
10 the major surfaces of the substrate from being scratched during this process.

11         In one embodiment, the heating and cooling of the substrate and waste pieces is  
12 accomplished without physically contacting the data recording surfaces of the substrate.

13         After the substrate is separated from the inner and outer waste pieces, an  
14 underlayer (e.g. Cr, NiP, NiAl, a Cr alloy or other material), a magnetic alloy (e.g. a Co  
15 or Fe alloy) and a protective overcoat (e.g. carbon, hydrogenated carbon, or a ceramic  
16 material such as  $ZrO_2$ ) are deposited, in that order, onto the substrate to thereby form a  
17 magnetic disk. This can be accomplished by sputtering, evaporation, ion plating, or other  
18 vacuum deposition processes.

## 19 20 Brief Description of the Drawings

21         Fig. 1 illustrates a work piece comprising cuts in accordance with the prior art.

22         Figs. 2A and 2B illustrate in cross section a work piece being separated from an  
23 outer waste piece in accordance with the present invention.

1 Figs. 2A' and 2A'' illustrate in cross section and plan view, respectively, a work  
2 piece being separated from an outer waste piece using a hot plate that is modified in  
3 accordance with an alternate embodiment of the invention.

4 Figs. 3A and 3B illustrate in cross section a work piece being separated from an  
5 inner waste piece in accordance with the invention.

6 Fig. 4 illustrates in cross section the work piece of Figs. 2 and 3 after the work  
7 piece has been separated from inner and outer waste pieces (thereby leaving a substrate as  
8 the product piece), and after an underlayer, magnetic layer and protective overcoat are  
9 deposited on the substrate.

10 These drawings are not drawn to scale.

#### 11 Detailed Description

12 A method in accordance with the present invention comprises cutting a work  
13 piece 10 to thereby form cuts 12, 14 (Fig. 2). In one embodiment, work piece 10 is a  
14 glass square, e.g. 110 mm by 110 mm, and 1 mm thick. However, these dimensions are  
15 merely exemplary, as is the shape of work piece 10. Glass square 10 can be formed by  
16 cutting or breaking square 10 out of a much larger glass sheet. This glass sheet can be  
17 formed by drawing, pressing, floating or other methods.

18 Cuts 12, 14 can be provided using any of a number of techniques. For example,  
19 cuts 12, 14 can be formed using radiant energy, e.g. a laser. In one such embodiment, a  
20 scribe line can be provided by applying a laser beam from a CO<sub>2</sub> laser against work piece  
21 10 followed by a cooling jet of air and/or water immediately behind the laser. This  
22 typically forms a crack through some, but not all, of the thickness of the glass. Next, the  
23 crack can be propagated from the scribe line all the way through the thickness of work

1 piece 10 by applying a second laser beam along the scribe line. (In lieu of or in addition  
2 to air or water, other gases or liquids, e.g. alcohol or hydrocarbons such as methanol or  
3 ethanol can be used. These materials evaporate rapidly.)

4 The laser can be applied to work piece 10 using a technique similar to the one  
5 described in U.S. Patent Application 09/407,003, filed September 28, 1999 by Hsieh et  
6 al., incorporated herein by reference.

7 Alternatively, cuts 12, 14 can be formed by initially mechanically scribing work  
8 piece 10, and then passing a laser over the scribe line. Alternatively, cuts 12, 14 can be  
9 formed by forming a scribe line in work piece 10, and then thermally stressing the work  
10 piece material at the location of the scribe lines. Cut 12 is typically 65, 84 or 95 mm in  
11 diameter. Cut 14 typically has a diameter of 20 or 25 mm. (These are standard outer and  
12 inner diameters for magnetic disks. However, cuts 12 and 14 can have other diameters as  
13 well.)

#### 14 15 Separation of the Substrate from the Waste Pieces

16 After forming cuts 12, 14, it is necessary to separate outer waste piece 16 from the  
17 remainder of work piece 10. It is also necessary to separate inner waste piece 18 from  
18 work piece 10. In one embodiment, this is accomplished using the following technique.

19 First, outer waste piece 16 is heated relative to the portion 20 of work piece 10  
20 that is ultimately used as a disk substrate. Typically, the difference between the  
21 temperature of outer waste piece 16 and portion 20 is between 150 and 200°C. (If this  
22 temperature difference is too low, there will be insufficient clearance to permit removal  
23 of waste piece 16.) The temperature difference between waste piece 16 and portion 20



1 can be greater than 200°C, but one must take care to ensure that stresses thermally  
2 induced in the glass do not warp or otherwise damage the substrate. It is expected that as  
3 laser cutting technology improves, the quality of the cuts that can be formed with a laser  
4 will also improve, and the temperature differentials that can be used to separate substrates  
5 from waste pieces will decrease.

6 In one embodiment, waste piece 16 is heated by placing waste piece 16 against a  
7 heating element. This heating element can be a hot plate 22, e.g. made of aluminum or  
8 other thermally conductive material. Since waste piece 16 will ultimately be thrown out,  
9 it does not matter whether its surface is damaged due to contact with hot plate 22. By  
10 heating waste piece 16 to a temperature as described above, waste piece 16 will expand  
11 sufficiently, relative to substrate 20, such that substrate 20 (and waste piece 18) can be  
12 separated from waste piece 16 simply by lifting substrate 20. (As shown in Fig. 2B,  
13 substrate 20 and waste piece 18 can be separated from waste piece 16 by using a vacuum  
14 grip 24 to lift waste piece 18. Since waste piece 18 firmly contacts substrate 20, substrate  
15 20 is also lifted out of waste piece 16 during this process. Advantageously, the data  
16 recording surfaces of substrate 20 are not mechanically contacted during this process.  
17 Alternatively, waste piece 18 (and substrate 20) can be gripped as shown in Figs. 3A and  
18 3B, described below.)

19 In one embodiment, substrate 20 can be lifted out of waste piece 16 after waste  
20 piece 16 has been in contact with hot plate 22 for a time period of about two to three  
21 seconds. However, time periods other than two to three seconds can be used. It is  
22 desirable that this time period is sufficiently long for heat to diffuse through the thickness  
23 of waste piece 16 prior to lifting substrate 20 out of waste piece 16.

1 In one embodiment, hot plate 22 has an inner opening 22a that has a diameter D1  
2 of about 99 mm. In other words, diameter D1 of opening 22a is slightly larger than  
3 diameter D2 of substrate 20. This helps to ensure that substrate 20 is not heated during  
4 this process.

5 In one embodiment, the difference between diameter D1 and diameter D2 is  
6 greater than the work piece thickness T. This ensures that when heating waste piece 16,  
7 heat can diffuse all of the way through the thickness of waste piece 16 before that heat  
8 has a chance to diffuse into substrate 20. Thus, the entire thickness of waste piece 16 can  
9 be heated without having heat diffuse into substrate 20 to expand substrate 20.

10 The difference between diameter D1 and diameter D2 also provides sufficient  
11 clearance such that the process described herein can be easily automated and performed  
12 by machinery. In other words, work piece 10 can be placed onto hot plate 22 by robotic  
13 equipment without putting substrate 20 in contact with hot plate 22.

14 Hot plate 22 typically has a square-shaped outer perimeter 22b that surrounds the  
15 outer, square-shaped perimeter of waste piece 16. This has the following advantage. If  
16 hot plate 22 did not laterally surround the outer perimeter of waste piece 16, the  
17 outermost portion of waste piece 16 would not be adequately heated. Thus, the inner  
18 portion of waste piece 16 would expand relative to the outer portion of waste piece 16,  
19 and this might cause waste piece 16 to crack and generate chips.

20 When separating waste piece 16 from substrate 20, it is not necessary to cool  
21 substrate 20 while heating waste piece 16 if waste piece 16 is heated to a sufficient  
22 temperature (e.g. about 200°C). However, in an alternate embodiment, waste piece 16  
23 can be heated to a temperature less than the desired temperature differential (instead of

200°C), and substrate 20 can be cooled (e.g. with a cold gas or liquid) to provide an appropriate temperature differential between waste piece 16 and substrate 20.

As seen in Fig. 2, cut 12 between waste piece 16 and substrate 20 is at an angle that facilitates the lifting of substrate 20 out of waste piece 16. However, in other embodiments, cut 12 is not at an angle.

After waste piece 16 is separated from substrate 20, it is necessary to separate waste piece 18 from substrate 20. In one embodiment, this is accomplished by heating substrate 20 relative to waste piece 18, cooling waste piece 18 relative to substrate 20, or both cooling waste piece 18 and heating substrate 20. (This heating and cooling can be accomplished either simultaneously or other than simultaneously).

In the embodiment described below, substrate 20 is heated to a temperature less than 200°C, e.g. 125°C. (Waste piece 18 is cooled during this embodiment so that the total temperature differential between waste piece 18 and substrate 20 is about 200°C.) It is advantageous to avoid subjecting substrate 20 to large temperature cycles. In particular, it is easier to implement a manufacturing process that does not require ramping temperatures up and down by 200°C. Also, it takes less time to heat substrate 20 to a temperature that is less than 200°C than it takes to heat substrate 20 to 200°C.

Another advantage to minimizing the temperature swing of substrate 20 is that when one heats glass, the entire surface of the glass is placed in compression. If the glass is cooled too rapidly, the glass is in tension, which is harmful, especially if there is any preexisting damage, because rapid cooling can propagate cracks.

Referring to Fig. 3A, in one embodiment substrate is separated from waste piece 18 by holding substrate 20 over a second hot plate 30 (Fig. 3A). Advantageously, the

1 data recording surfaces of substrate 20 are in proximity to, but do not contact, hot plate  
2 30. (Support 31 extending from the top surface of hot plate 30 contacts a small portion of  
3 substrate 20 at its inner diameter. This is not a problem, since this is the portion of  
4 substrate 20 that will eventually be mounted on a spindle within a disk drive.) Second  
5 hot plate 30 heats substrate 20 to a temperature of about 125°C. Simultaneously, waste  
6 piece 18 is cooled by applying a cooling element 32 against waste piece 18. Cooling  
7 element 32 can be a thermoelectric cooling element 32, e.g. as described by Robert  
8 Smythe in “Cooling: Thermoelectric Cooling for Photonics Applications”, published in  
9 The Photonics Design and Applications Handbook in 1997, incorporated herein by  
10 reference. Alternatively, instead thermoelectrically cooling, cooling element 32 can  
11 contain conduits or reservoirs in which a coolant circulates. Cooling element 32 can be  
12 cooled in other ways as well, e.g. by placing element 32 against cold material, e.g. liquid  
13 nitrogen. In one embodiment, inner waste piece 18 is cooled to about -75°C, e.g. by  
14 placing cooling element 32 against waste piece 18 for about two to three seconds. The  
15 application of heat to substrate 20 and cooling of waste piece 18 causes substrate 20 to  
16 expand relative to waste piece 18, and waste piece 18 to contract relative to substrate 20.  
17 Thus, a clearance develops between substrate 20 and waste piece 18 so that waste piece  
18 18 can be pushed upward and out of the opening in substrate 20, e.g. by raising cooling  
19 element 32 (Fig. 3B).

20 As shown in Fig. 3B, waste piece 18 is removed by raising cooling element 32  
21 upon which waste piece 18 rests. Waste piece 18 is pushed against a vacuum channel 35  
22 that is part of a gripping structure 36. After waste piece 18 is pushed against vacuum  
23 channel 35, gripping structure 36 is raised, thereby lifting both waste piece 18 and

1 substrate 20. (An outer vacuum channel 37 facilitates lifting of substrate 20.) Gripping  
2 structure 36 does not contact the data recording surfaces of substrate 20, so the data  
3 recording surfaces are not damaged or scratched during lifting.

4 As mentioned above, the temperature differential between the temperature of  
5 substrate 20 and inner waste piece 18 is about 200°C. However, as mentioned above, as  
6 the quality of laser cuts improves with technology, it is expected that separating substrate  
7 20 from waste piece 18 can be accomplished with a lower temperature differential.

8 In one embodiment, the diameter D3 of cooling element 32 is smaller than the  
9 diameter D4 of waste piece 18. This is because one would not want to cool the inner  
10 diameter of substrate 20 (e.g. to ensure that the inner diameter of substrate 20 does not  
11 thermally contract, and to avoid tensile stress in the material of substrate 20). In one  
12 embodiment, the difference between diameters D3 and D4 is greater than or equal to the  
13 thickness of waste piece 18. This ensures that the entire thickness of waste piece 18 can  
14 be cooled before heat starts to diffuse out of substrate 20 and cause a temperature drop in  
15 substrate 20.

16 It is noted that the data recording surfaces of substrate 20 are never in contact  
17 with structures that could scratch these surfaces. Accordingly, the method of the present  
18 invention represents an improvement over other processes in which cooling or heating  
19 elements are placed against the surfaces of substrates.

## 20 21 Processing After Separation of the Substrate from the Waste Pieces

22 After substrate 20 is separated from waste pieces 16, 18, substrate 20 can be  
23 subjected to additional processing, e.g. an edge polishing process as described by Bajorek

in U.S. Patent Application 09/369,030, filed August 4, 1999, incorporated herein by reference. This edge polishing process rounds the corners of the inner and outer edges of substrate 20. In lieu of or in addition to such edge polishing, chamfers can be placed at the inner and outer diameters of substrate 20. Substrate 20 can then be subjected to various lapping and/or polishing steps as required.

In some embodiments, substrate 20 is subjected to chemical strengthening. During chemical strengthening, substrate 20 is immersed in a molten potassium salt bath. This results in the formation of a compression layer at or near the surface of substrate 20 for strengthening substrate 20.

Thereafter, an underlayer 40 (e.g. Cr, a Cr alloy, NiP, NiAl, or other appropriate material), a magnetic alloy 42 (e.g. a Co or Fe alloy) and a protective overcoat 44 (e.g. carbon or hydrogenated carbon) are deposited on substrate 20, in that order, to form a magnetic disk 46 (Fig. 4). This can be accomplished using a vacuum deposition technique such as sputtering, evaporation, ion plating, or other method. An example of a method for completing the manufacture of a magnetic disk is described in U.S. Patent Application 08/894,753, filed by Bertero et al. on December 4, 1997, incorporated herein by reference.

#### Alternative Embodiment of the Method for Separating Substrate 20 from Waste Piece 16

It has been found that float or drawn glass sheets that have not been properly annealed often contain internal stresses. These stresses can cause glass to warp when the glass is heated to a sub-annealing temperature. In fact, it has been observed that heating of glass sheets that have not been properly annealed can cause a glass sheet to warp by as much as 2 mm from the highest to lowest point over a 100x100 mm area at a temperature

as low as 200°C. (The glass sheet can warp for other reasons, such as non-uniform heating, non-uniform composition or other factors.) If warping occurs when work piece 10 is placed against hot plate 22, waste piece 16 will not be heated uniformly. As a result, waste piece 16 could shatter or warp into a shape that interferes with the separation of waste piece 16 from substrate 20. (This problem is more severe if work piece 10 is made thicker.) Accordingly, in one embodiment of the invention, hot plate 22 comprises channel 23 (Fig. 2A') for holding waste piece 16 flush against hot plate 22 and for preventing waste piece 16 from warping. In one embodiment, a portion 23a of channel 23 extends in the shape of a circle laterally surrounding cut 12. Portion 23a is typically milled into the surface of hot plate 22. In another embodiment, channel 23 terminates in a set of separate regions (e.g. discrete vacuum openings) at the surface of hot plate 22. In general, any size, shape or configuration of channels can be used provided that the channel(s) hold the substrate to a sufficient degree to prevent excess warping. In any embodiment, a vacuum <sup>can be</sup> applied using conventional means (e.g. a mechanical pump) to inlet 23b of channel 23. The vacuum is preferably applied immediately after the glass touches hot plate 22. (A delay in the application of the vacuum could enable the glass to warp and subsequently prevent the vacuum from acting on work piece 10.)

Because areas of waste piece 16 directly above portion 23a of channel 23 <sup>do</sup> ~~so~~ not directly contact the heat source, it is conceivable that non-uniform stresses around these areas can lead to cracking. To prevent this, width W of portion 23a is minimized. In general, width W should not be greater than thickness T of work piece 10. If more force is needed to hold waste piece 16 flat against hot plate 20, the strength of the vacuum should be increased or separate narrow vacuum channels should be provided in other

RT. 4/21/00  
JM  
4/21/00

RT. 4/21/00  
JM  
4/21/00

regions of hot plate 22. Lastly, the total vacuum force exerted on the glass (i.e. the product of the vacuum pressure times the area) and the pattern of the vacuum channels should not hinder the glass from expanding relatively freely during heating.

While the invention has been described with respect to specific embodiments, those skilled in the art will recognize that changes can be made in form and detail without departing from the spirit and scope of the invention. For example, the glass work piece can be any form of glass, e.g. aluminosilicate glass, borosilicate glass, or other silica based glass comprising any of a number of additives. The glass can be formed using different techniques, and can be cut using different techniques. The product piece can have a shape other than that of a disk.

While one embodiment of the invention uses a work piece that is 1 mm thick, other thicknesses can be used as well. In one embodiment, a thicker work piece e.g. 1.3 mm thick, can be used. When using a thicker work piece, it is advantageous to apply heat both sides of the work piece (or cool both sides of the work piece).

While one embodiment uses a temperature differential of 200°C, it is stressed that other temperature differentials can be used. In some embodiments, the temperature difference is preferably approximately 100°C or greater, more preferably approximately 125°C or greater, and most preferably approximately 150°C or greater. Moreover, while heating or cooling alone can be used, in some embodiments it is desirable to limit the temperature cycle to which a given piece of glass is subjected for the reasons discussed earlier. In such embodiments, a piece is preferably subjected to a temperature cycle of approximately 200°C or less, more preferably approximately 150°C or less, and most preferably approximately 125°C or less. If a greater temperature difference is needed, the



1 other piece can be heated or cooled to achieve the desired total temperature difference as  
2 described herein. Different amounts of increases and/or decreases in the product piece  
3 and waste piece temperatures can be used to achieve these other temperature differentials.

4 In lieu of using a hot plate, heating waste piece 16 and/or substrate 20 can be  
5 accomplished by infrared heating, resistive heating or hot air. In lieu of using a  
6 thermoelectric cooling element, waste piece 18 can be cooled using dry ice, liquid  
7 nitrogen, cold gas (e.g. cold air or nitrogen), or placing a cooled piece of thermally  
8 conductive material (e.g. a metal such as aluminum or copper) against waste piece 18.  
9 The thermally conductive material can be cooled by placing it in liquid nitrogen.

10 While Figs. 2A and 2B show substrate 20 being lifted out of contact with waste  
11 piece 16, in another embodiment, substrate 20 is lowered or dropped out of contact with  
12 waste piece 16. Also, waste piece 16 can be raised or lowered out of contact with  
13 substrate 20. Further, waste piece 16 can be permitted to fall out of contact with substrate  
14 20 by the force of gravity.

15 Similarly, while Figs. 3A and 3B show waste piece 18 being lifted out of contact  
16 with substrate 20, in other embodiments waste piece 18 is lowered out of contact with  
17 substrate 20. (Waste piece 18 can also be permitted to fall out of contact with substrate  
18 20 by the force of gravity.) Similarly, substrate 20 can be raised or lowered out of  
19 contact with waste piece 18.

20 The lifting or lowering of the substrate and/or waste piece can be accomplished  
21 with other combinations of platforms holding, raising or lowering one or both of these  
22 pieces and/or vacuum chucks holding, raising or lowering one or both of these pieces.  
23 Also, the substrate and/or waste piece can be mechanically manipulated using other

mechanisms as well, e.g. mechanical fingers that grasp the outer or inner diameter of these structures.

While Figs. 2 and 3 show the various heating and cooling elements applied to the bottom side of work piece 10, in other embodiments, the various heating and cooling elements are applied to the <sup>top</sup>~~bottom~~ side of work piece 10. Alternatively, the heating and cooling elements can be applied to both sides of work piece 10.

JH  
4/21/00  
R.J. 4/21/00

Instead of heating waste piece 18, substrate 20 can be cooled. (Care should be taken to avoid causing thermally induced stresses in substrate 20 that would cause substrate 20 to warp or crack.) Accordingly, all such changes come within the present invention.



1  
2           5.       Method of claim 4 further comprising:  
3           gripping said inner waste piece with a vacuum grip after said heating of said  
4       outer waste piece; and  
5           raising said inner waste piece to thereby separate the inner waste piece and middle  
6       portion from said outer waste piece.  
7

8           6.       Method of claim 1 wherein said heating the middle portion and cooling the  
9       inner waste piece is accomplished by:  
10          placing said middle portion proximate to but not in contact with a heating  
11       element;  
12          placing a cooling element against the inner waste piece; and  
13          lifting the inner waste piece relative to the middle portion to thereby separate the  
14       inner waste piece from the middle portion.  
15

16          7.       Method of claim 1 further comprising depositing a magnetic layer on the  
17       middle portion after the middle portion has been separated from the inner and outer waste  
18       pieces.  
19

20          8.       Method of claim 7 further comprising forming an underlayer between the  
21       middle portion and the magnetic layer, and forming a protective overcoat over the  
22       magnetic layer.  
23

1           9.       Method of claim 1 wherein said heating the outer waste piece comprises:  
2           placing said outer waste piece against a heating element, said heating element  
3           comprising one or more channels formed therein; and  
4           applying a vacuum to said one or more channels to hold said outer waste piece  
5           against said heating element.

7           10.      Method of claim 1 wherein said outer cut circumferentially surrounds said  
8           middle portion.

10          11.      Method of claim 1 wherein the temperature difference between the middle  
11          piece and the waste piece that said middle piece is being separated from during said  
12          separating is greater than about 100 °C.

14          12.      Method of claim 1 wherein the temperature difference between the middle  
15          piece and the waste piece that said middle piece is being separated from during said  
16          separating is greater than about 125 °C.

18          13.      Method of claim 1 wherein the temperature difference between the middle  
19          piece and the waste piece that said middle piece is being separated from during said  
20          separating is greater than about 150 °C.

22          14.      Method of claim 1 wherein said middle piece is subjected to a temperature  
23          cycle less than about 200 °C during said method.

1  
2 15. Method of claim 1 wherein said middle piece is subjected to a temperature  
3 cycle less than about 150 °C during said method.

4  
5 16. Method of claim 1 wherein said <sup>middle</sup>~~middle~~ piece is subjected to a temperature  
6 cycle less than about 125 °C during said method.

JH  
4/21/00  
RT 4/21/00

7  
8 17. Method comprising:  
9 providing a glass work piece that surrounds a waste piece;  
10 heating the glass work piece without mechanically contacting the major surfaces  
11 of said work piece;  
12 cooling the waste piece, whereby the waste piece contracts relative to the work  
13 piece, and the work piece expands relative to the waste piece; and  
14 separating the work piece from the waste piece.

15  
16 18. Method of claim 17 wherein the temperature difference between the work  
17 and waste pieces is greater than about 100 °C during said separating.

18  
19 19. Method of claim 17 wherein the temperature difference between the work  
20 and waste pieces is greater than about 125 °C during said separating.

21  
22 20. Method of claim 17 wherein the temperature difference between the work  
23 and waste pieces is greater than about 150 °C during said separating.

1  
2           21.     Method of claim 17 wherein said work piece is subjected to a temperature  
3 cycle less than about 200 °C during said method.

4  
5           22.     Method of claim 17 wherein said work piece is subjected to a temperature  
6 cycle less than about 150 °C during said method.

7  
8           23.     Method of claim 17 wherein said work piece is subjected to a temperature  
9 cycle less than about 125 °C during said method.

10  
11          24.     Method comprising:  
12                 providing a work piece comprising a crack extending through the thickness of the  
13 work piece, said crack having a closed shape such that the crack surrounds a first portion  
14 of said work piece and is surrounded by a second portion of said work piece.

15                 causing a temperature differential between said first and second portions such that  
16 the first portion has a greater temperature than the second portion, thereby facilitating the  
17 separation of the first and second portions.

18  
19          25.     Method of claim 24 wherein said causing comprises heating said second  
20 portion.

21  
22          26.     Method of claim 24 wherein said causing comprises cooling said first  
23 portion.

1  
2           27.     Method of claim 24 wherein said causing comprises heating said second  
3 portion and cooling said first portion.  
4

5           28.     Method of claim 24 wherein said first portion is disk shaped.  
6

7           29.     Method of claim 24 wherein said second portion is disk shaped.  
8

9           30.     Method of claim 24 wherein the temperature difference between the work  
10 and waste pieces is greater than about 100 °C.  
11

12           31.     Method of claim 24 wherein the temperature difference between the work  
13 and waste pieces is greater than about 125 °C.  
14

15           32     Method of claim 24 wherein the temperature difference between the work  
16 and waste pieces is greater than about 150 °C.  
17

18           33.     Method of claim 24 wherein said work piece is subjected to a temperature  
19 cycle less than about 200 °C during said step of causing a temperature difference.  
20

21           34.     Method of claim 24 wherein said work piece is subjected to a temperature  
22 cycle less than about 150 °C during the step of causing a temperature difference.  
23



1           35.     Method of claim 24 wherein said work piece is subjected to a temperature  
2 cycle less than about 125 °C during the step of causing a temperature difference.

3  
4           36.     Method comprising:  
5           providing a temperature difference between a product piece and a waste piece so  
6 that said waste piece and product piece can be moved relative to one another;  
7           moving one of said product piece or said waste piece so that said moved product  
8 piece or waste piece is in proximity to a vacuum chuck; and  
9           causing said vacuum chuck to hold said moved product piece or waste piece.

10  
11           37.     Method of claim 36 wherein said vacuum chuck comprises two vacuum  
12 channels that are displaced from one another so that said vacuum chuck can hold both the  
13 product piece and the waste piece while the product and waste pieces are displaced  
14 relative to one another.

15  
16           38.     Method of claim 37 further comprising using said vacuum chuck to  
17 transport the waste and product pieces after the waste and product pieces are displaced  
18 from one another.

19  
20           39.     Method of claim 36 wherein the product piece is a glass substrate.

21  
22           40.     Method comprising:  
23           providing a work piece and a waste piece;

1 placing one of the waste piece or the product piece adjacent to a temperature  
2 element, said temperature element changing the temperature of the adjacent waste piece  
3 or product piece so that the waste piece and product pieces can be displaced relative to  
4 one another; and

5 moving the temperature element so that the temperature element moves the  
6 adjacent waste piece or product piece, whereby the waste and product pieces are  
7 displaced relative to one another.

8  
9 41. Method of claim 40 wherein said placing comprises placing the waste  
10 piece over the temperature element.

11  
12 42. Method of claim 40 wherein the product piece is a substrate.

13  
14 43. Method of claim 40 wherein the temperature element is a cooling element.

15  
16 44. Method of claim 40 wherein said moving the temperature element  
17 comprises lifting the temperature element while the waste piece rests on the temperature  
18 element.

19  
20 45. Method for heating a work piece with a heating element, said heating  
21 element comprising channels extending to the surface of said heating element, said  
22 method comprising:

1 placing a work piece against said heating element to thereby heat said work piece;  
2 and  
3 applying a vacuum to said channels to hold said work piece against said heating  
4 element.  
5

6 46. Method of claim 45 wherein said vacuum results in a force that  
7 substantially prevents said work piece from warping.  
8

9 47. Method of claim 45 wherein said work piece comprises a waste piece  
10 surrounding a product piece, said heating of said work piece facilitating separating said  
11 product piece from said waste piece.  
12

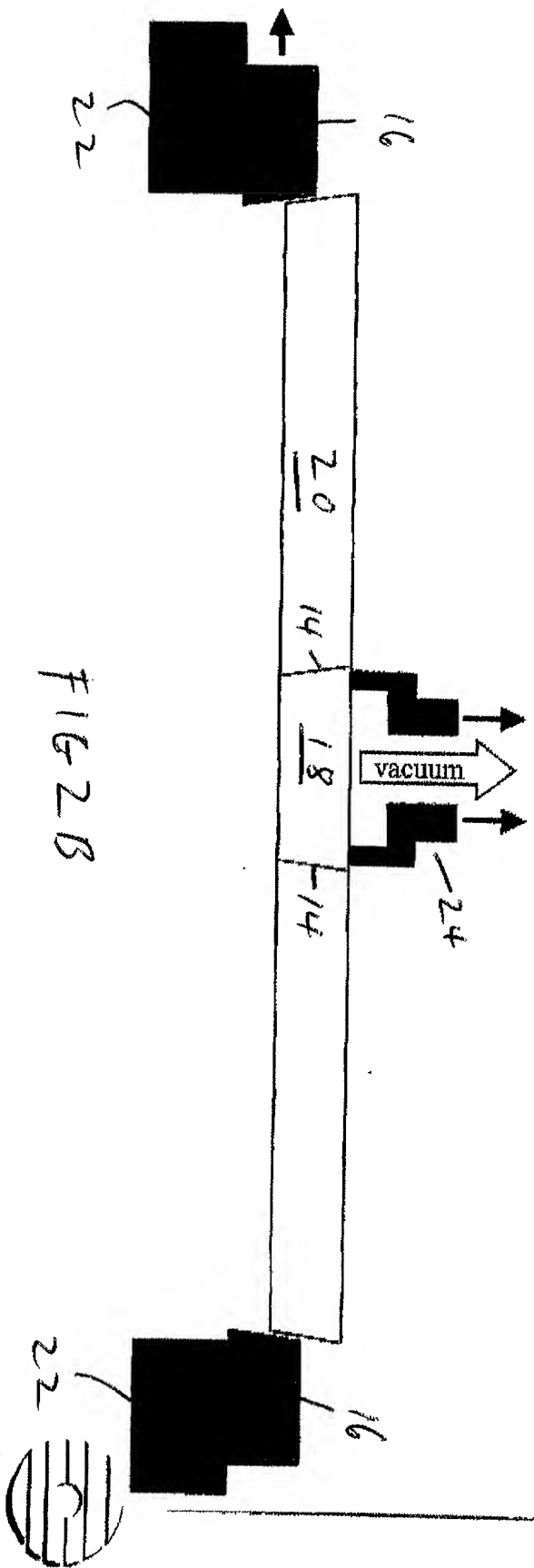
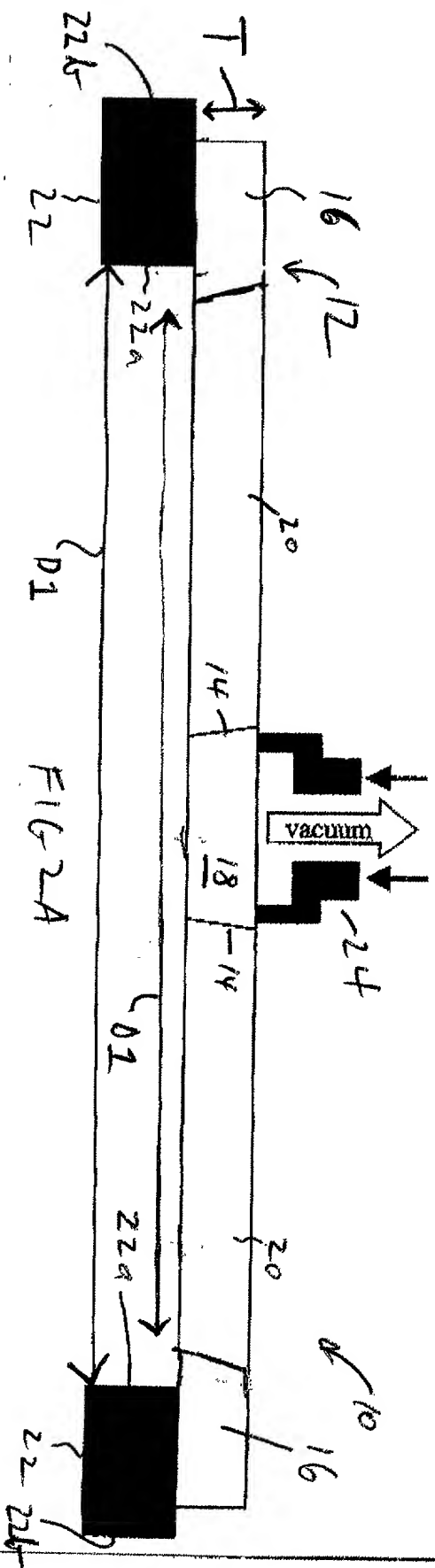
13 48. Apparatus comprising:  
14 a hot plate for heating a work piece; and  
15 a vacuum channel extending to a surface of said hot plate for holding said work  
16 piece flush against said hot plate.  
17

18 49. Apparatus of claim 48 wherein said hot plate only heats a portion of said  
19 work piece at the periphery of said work piece but not a centrally located portion of said  
20 work piece.

## Abstract

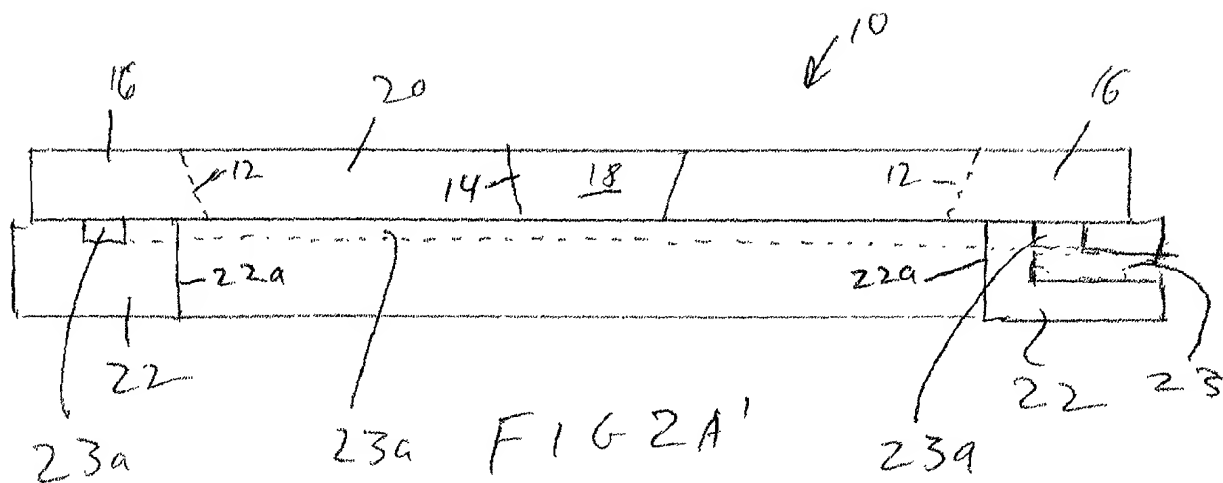
A method for forming a magnetic disk comprises the following steps. First, an inner and outer cut is provided in a work piece. The waste piece thus comprises an outer waste piece, an inner waste piece, and a region between the inner and outer waste pieces that is to be used as a substrate for manufacturing a magnetic disk. The outer waste piece is separated from the substrate by applying a hot plate against the outer waste piece, thereby causing it to thermally expand and separate from the substrate. The substrate is then placed over (but not in contact with) a hot plate, while a cooling element is placed on the inner waste piece. This causes the substrate to thermally expand while the inner waste piece thermally contracts. Thus, a gap forms between the substrate and inner waste piece, thereby permitting the separation of the inner waste piece from the substrate.







005490-23003360







Please type a plus sign (+) inside this box → ☐

PTO/SB/01 (12-97)

Approved for use through 9/30/00. OMB 0651-0032  
Patent and Trademark Office U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995 no persons are required to respond to a collection of information unless it contains a valid OMB control number

<b>DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION (37 CFR 1.63)</b>	<b>Attorney Docket Number</b>	K2000003	
	<b>First Named Inventor</b>	John Hsieh	
	<b>COMPLETE IF KNOWN</b>		
	<b>Application Number</b>	/	
	<b>Filing Date</b>		
	<b>Group Art Unit</b>		
<input checked="" type="checkbox"/> Declaration Submitted with Initial Filing	<input type="checkbox"/> Declaration Submitted after Initial Filing (surcharge (37 CFR 1.16 (e)) required)	<b>Examiner Name</b>	

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**Removal of Enclosed Glass Parts After Cutting  
Using Heating and Cooling Techniques**

the specification of which

(Title of the invention)

☒ is attached hereto  
OR☐ was filed on (MM/DD/YYYY) as United States Application Number or PCT International

Application Number and was amended on (MM/DD/YYYY) (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate or 365(e) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate or of any PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application Number(s)	Country	Foreign Filing Date (MM/DD/YYYY)	Priority Not Claimed	Certified Copy Attached?	
				YES	NO
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

☐ Additional foreign application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below.

Application Number(s)	Filing Date (MM/DD/YYYY)	<input type="checkbox"/> Additional provisional application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto

[Page 1 of 2]

Burden Hour Statement: This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

Please type a plus sign (+) inside this box → ☒

PTO/SB/01 (12-97)  
 Approved for use through 9/30/00, OMB 0651-0032  
 Patent and Trademark Office U.S. DEPARTMENT OF COMMERCE  
 Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

**DECLARATION — Utility or Design Patent Application**

I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

U.S. Parent Application or PCT Parent Number	Parent Filing Date (MM/DD/YYYY)	Parent Patent Number (if applicable)

☐ Additional U.S. or PCT international application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

As a named inventor, I hereby appoint the following registered practitioner(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: ☐ Customer Number  OR ☒ Registered practitioner(s) name/registration number listed below.

Place Customer Number, Bar Code Label here.

Name	Registration Number	Name	Registration Number
Kenneth Leeds	30,566	Keith Askoff	33,828

☐ Additional registered practitioner(s) named on supplemental Registered Practitioner Information sheet PTO/SB/02C attached hereto.

Direct all correspondence to: ☐ Customer Number  or Bar Code Label OR ☒ Correspondence address below.

Name	Kenneth Leeds				
Address	P.O. Box 2819				
Address					
City	Sunnyvale	State	CA	ZIP	94087-0819
Country	US	Telephone	408-732-9500	Fax	408-736-7052

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Name of Sole or First Inventor:

☐ A petition has been filed for this unsigned inventor.

Given Name (first and middle (if any))		Family Name or Surname	
John		Keith	
Inventor's Signature	Date		4/21/00
Residence: City	San Jose	State	CA
		Country	US
Post Office Address	3288 Tulipwood Ln		
Post Office Address			
City	San Jose	State	CA
		ZIP	95132
		Country	US

☒ Additional inventors are being named on the 1 supplemental Additional inventor(s) sheet(s) PTO/SB/02A attached hereto.

Please type a plus sign (+) inside this box → ☐

PTO/SB/02A (3-97)

Approved for use through 9/30/98. CMB 0651-0032

Patent and Trademark Office, U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

## DECLARATION

ADDITIONAL INVENTOR(S)  
Supplemental Sheet

Page 1 of 1

Name of Additional Joint Inventor, if any:				<input type="checkbox"/> A petition has been filed for this unsigned inventor			
Given Name (first and middle (if any))				Family Name or Surname			
Robert M.				Tierney			
Inventor's Signature	Robert M. Tierney			Date	4/21/00		
Residence: City	Fremont	State	CA	Country	US	Citizenship	US
Post Office Address 33206 Lake Champlain Court							
Post Office Address							
City	Fremont	State	CA	ZIP	94555	Country	US
Name of Additional Joint Inventor, if any:				<input type="checkbox"/> A petition has been filed for this unsigned inventor			
Given Name (first and middle (if any))				Family Name or Surname			
Inventor's Signature				Date			
Residence: City		State		Country		Citizenship	
Post Office Address							
Post Office Address							
City		State		ZIP		Country	
Name of Additional Joint Inventor, if any:				<input type="checkbox"/> A petition has been filed for this unsigned inventor			
Given Name (first and middle (if any))				Family Name or Surname			
Inventor's Signature				Date			
Residence: City		State		Country		Citizenship	
Post Office Address							
Post Office Address							
City		State		ZIP		Country	

Surden Hour Statement: This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.